

1. 封裝 Package

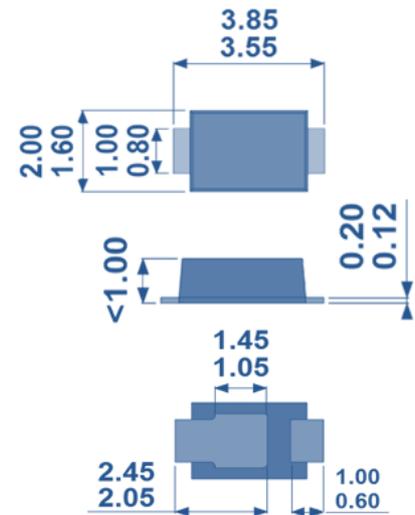
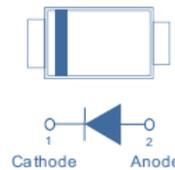
- 封裝方式 Method: SOD-123ST
- 封裝尺寸 Dimension: 如圖示

2. 產品特色 Features

- Fast switching speed
- Surface mount package ideally suited for automatic insertion
- Electrical identical standard JEDEC
- High conductor
- Lead-free & halogen-free parts, RoHS compliant

3. 機械數據 Mechanical Data

- Case: SOD-123ST, Plastic
- Terminals: Solderable per MIL-STD-750 Method 2026
- Polarity: Color band denotes cathode end



單位 Unit: millimeters

4. 極限值與電參數 Maximum Ratings & Electrical Characteristic

Parameter	Symbol	SS1040HE	SS1060HE	UNITS
Marking Code		EM	EN	-
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	40	60	Volts
Maximum RMS Voltage	V_{RMS}	28	42	Volts
Maximum DC Blocking Voltage	V_R	40	60	Volts
Maximum Average Forward Current	I_O	1		Amps
Peak Forward Surge Current: 8.3ms single half sine-wave superimposed on rated load	I_{FSM}	30		Amps
Maximum Forward Voltage at 1A	V_F	0.55	0.7	Volts
Maximum DC Reverse Current	I_R	100		μA
Typical Junction capacitance at $V_R=0V$, $f=1MHz$	C_j	155	125	pF
Typical Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	225		$^{\circ}C/W$
Junction to Case (Note 1)	$R_{\theta JC}$	20		
Operating Junction Temperature and Storage Temperature Range	T_J, T_{STG}	-55 to +150		$^{\circ}C$

Notes:

- (1) Mounted on 48cm² FR-4 PCB board.

5. 特性曲線 Rating & Characteristic Curves

Fig. 1 Forward Current Derating Curve

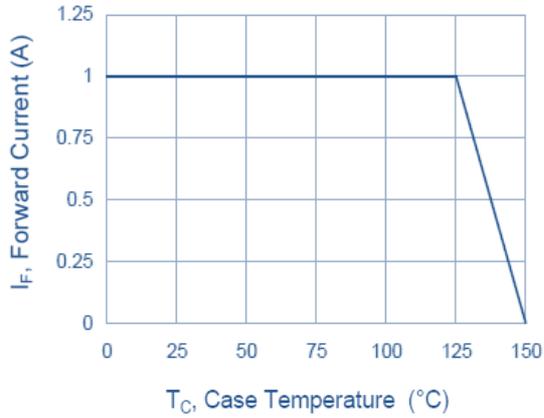


Fig. 2 Typical Junction Capacitance

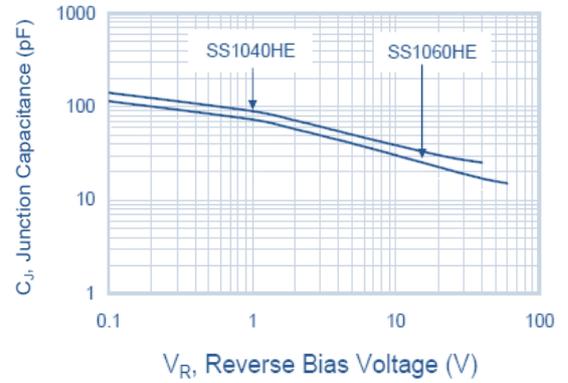


Fig. 3 Typical Reverse Characteristics

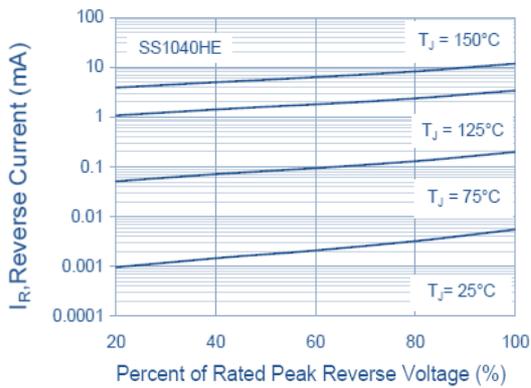


Fig. 4 Typical Reverse Characteristics

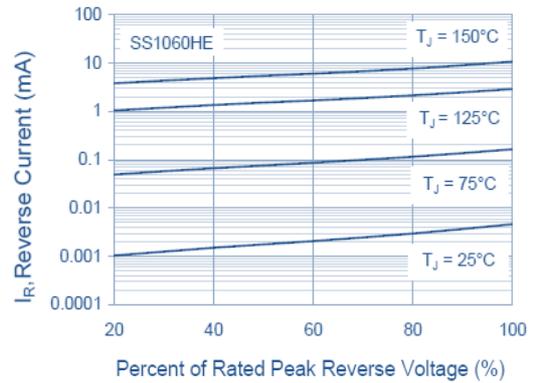


Fig. 5 Typical Forward Characteristics

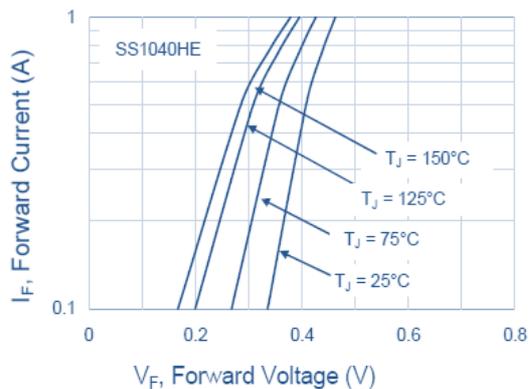
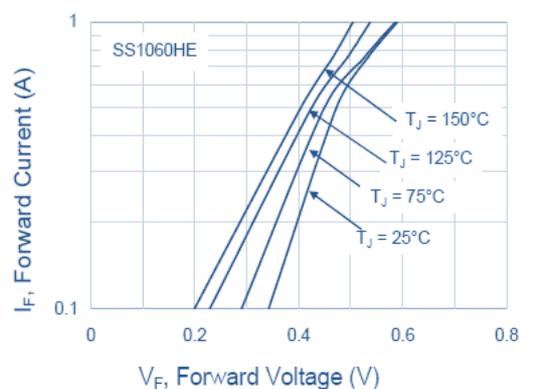
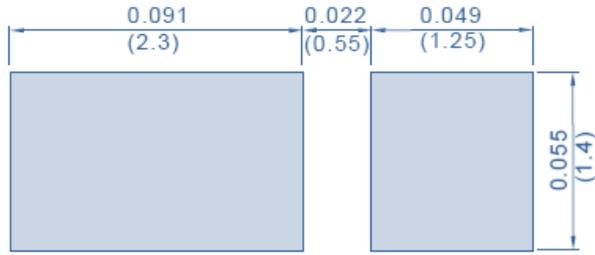


Fig. 6 Typical Forward Characteristics



Pad Layout



單位 Unit: inch(millimeters)